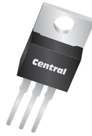
Material Composition Specification

TO-220 Case



Device average mass . . . . **1.89 g**

Fluctuation margin . . . . **+/-10%**

Component	Material	Material (%wt)	Material (mg)	Substance	CAS No.	Substance (%wt)	Substance (mg)	Substance (ppm)
active device	doped Si	0.3%	5.67	Si	7440-21-3	0.3%	5.67	3,006
bond wire	aluminum	0.14%	2.55	Al	7429-90-5	0.14%	2.55	1,352
leadframe	Cu alloy	66.89%	1261.86	Cu	7440-50-8	66.79%	1,260	667,944
				Fe	7439-89-6	0.003%	0.06	32
				P	7723-14-0	0.1%	1.8	954
die attach	high temperature solder	0.33%	6.21	Pb	7439-92-1	0.3%	5.74	3,043
				Sn	7440-31-5	0.02%	0.31	164
				Ag	7440-22-4	0.01%	0.16	82
encapsulation*	EMC	31.81%	600	silica	7631-86-9	23.22%	438	232,190
				epoxy resin	Proprietary	7.32%	138	73,156
				Sb_2O_3	1309-64-4	0.64%	12	6,361
				TBBA	79-94-7	0.64%	12	6,361
	EMC GREEN	31.81%	600	silica	7631-86-9	23.86%	450	238,552
				epoxy resin	Proprietary	4.93%	93	49,301
				epoxy polymer	Proprietary	2.39%	45	23,855
				Sb_2O_3	1309-64-4	0.54%	10.2	5,406
				carbon black	1333-86-4	0.1%	1.8	954
plating**	tin/lead process	0.54%	10.1	Sn	7440-31-5	0.43%	8.08	4,283
				Pb	7439-92-1	0.11%	2.02	1,071
	matte tin	0.54%	10.1	Sn	7440-31-5	0.54%	10.1	5,354

*EMC GREEN molding compound is Halogen-Free.

**For Lead Free plating, add suffix “PB FREE” to part number.
For Tin/Lead plating, add suffix “TIN/LEAD” to part number.
No suffix designation allows for the supply of either lead-free or tin/lead plated product depending on availability.

Disclaimer
The information provided in this Material Composition data sheet is, to the best of our knowledge, correct. However, there is no guarantee to completeness or accuracy, as some information is derived from data sources outside the company.

R4 (16-July 2018)